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32mm 低频玻璃封装应答机,只读 (RO)

特性

- 由获专利的半双工 (HDX) 技术提供的同类产品中最 佳性能
- 获专利的应答机调谐提供稳定的和高读取性能
- 80 位只读 (RO) 类型
- 64 位芯片 ID
- 对几乎所有非金属物质不敏感

应用范围

- 访问控制
- 车辆识别
- 集装箱跟踪
- 资产管理
- 废品管理

说明

德州仪器 (TI) 32mm 低频 (LF) 玻璃应答机提供出色性能并可在 134.2kHz 的共振频率上运行。此产品兼容 ISO/IEC 11784/11785 全球开放式标准。 德州仪器 (TI) LF 玻璃应答机使用 TI 获专利的调谐制造工艺生产以提供持续的读取性能。 送货前,将对此应答机进行全面的功能和参数测试,为用户提供他们希望从 TI 获得的高质量产品。



绝对最大额定值(1)

在自然通风温度范围内运行(除非另有说明)

		TRPGR30ATGB
T _A	工作温度	-25°C 至 70°C
T _{STG}	存储温度	-40°C 至 85°C

⁽¹⁾ 超出 *绝对最大额定值* 列出的值的应力可能会对器件造成永久损坏。 这些只是应力额定值,在这些额定值或者任何其它超过 *特性* 下所标明条件下的器件功能运行在此并未说明。 长时间运行在绝对最大额定条件下会影响设备的可靠性。

特征

参数	TRPGR30ATGB					
功能	只读					
存储器(位)	80 (64 位唯一 ID + 16 位 BCC)					
存储器(页)	1					
共振频率	134.6kHz					
调制	FSK (频移键控) 134.2kHz 和 124.2kHz					
发射原理	HDX (半双工)					
电源	由读取器信号供电 (无电池)					
典型读取范围	≤ 110cm ⁽¹⁾					
典型读取时间	70ms					
外壳材料	玻璃					
保护玻璃	密封					
电磁兼容性 (EMC)	己编辑代码不受自然电磁干扰或 X 射线的影响。					
信号穿透力	应答机能透过几乎全部非金属物质进行读取。					
机械冲击	IEC 68-2-27,测试 Ea;300g,3ms					
尺寸	Ø 3.85 ± 0.05mm x 31.2 ± 0.6mm					
重量	0.8g					

(1) 取决于使用所在国家的 RF 管理规定, 读取器天线配置和环境条件。



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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
TRPGR30ATGB	ACTIVE	RFIDT	TGB	0	2000	RoHS & Green	Call TI	N / A for Pkg Type	-25 to 70		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

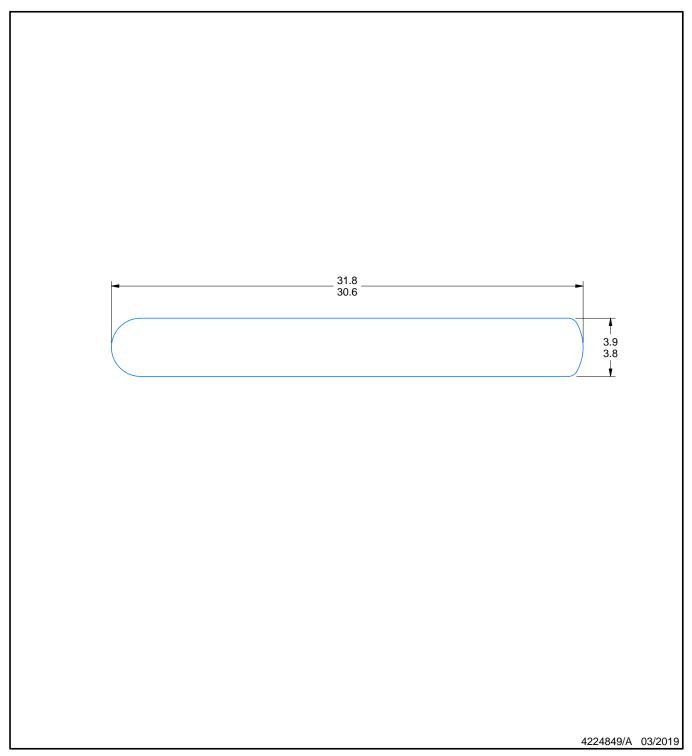
Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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RADIO FREQUENCY IDENTIFICATION



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
 2. This drawing is subject to change without notice.
- 3. HDX+ 32mm glass transponder with capacitor on die technology.



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